502991617 09/25/2014

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
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| NATURE OF CONVEYANCE: | ASSIGNMENT |

CONVEYING PARTY DATA

| Name | Execution Date |
|----------------|----------------|
| OH BYOUNG KWON | 09/17/2014 |
| CHUL JIN KIM | 09/17/2014 |
| JAE HYUK LEE | 09/17/2014 |
| KI MUN PAIK | 09/17/2014 |

RECEIVING PARTY DATA

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| State/Country: | KOREA, REPUBLIC OF | |

PROPERTY NUMBERS Total: 1

| Property Type | Number |
|---------------------|----------|
| Application Number: | 14495888 |

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|-------------------------|------------------------|--|
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| SIGNATURE: | /Young Seok Koo L0792/ | |
| DATE SIGNED: | 09/25/2014 | |

Total Attachments: 3

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> **PATENT** REEL: 033818 FRAME: 0233 502991617

ASSIGNMENT

WHEREAS, We(I), Oh Byoung KWON of Suwon-Si, Gyeonggi-Do, Republic of Korea, Chul Jin KIM of Suwon-Si, Gyeonggi-Do, Republic of Korea, Jae Hyuk LEE of Suwon-Si, Gyeonggi-Do, Republic of Korea, and Ki Mun PAIK of Suwon-Si, Gyeonggi-Do, Republic of Korea, are (am) the inventor(s) of an invention entitled "CAMERA MODULE AND PORTABLE ELECTRONIC DEVICE INCLUDING THE SAME" that is the subject matter of: (check all that apply)

| [X] | an application for Letters Patent which is identifiable in the United States Patent and Trademark Office by Application No. <u>14/495,888</u> filed on <u>September 25, 2014</u> , |
|-------------------------|---|
| [] | an application made under the Patent Cooperation Treaty which is identifiable at WIPO by Application No. PCT/filed on, |
| [] | an application for Letters Patent which is identifiable in the Patent Office of by Application No filed on; |
| the law Gyeon | EAS, <u>SAMSUNG ELECTRO-MECHANICS CO., LTD</u> ., a corporation organized and existing under s of <u>Korea</u> , and having offices at <u>Maeyoung-Ro 150 (Maetan-Dong), Youngtong-Gu, Suwon-Si, agi-Do, Republic of Korea</u> is desirous of acquiring the entire right, title and interest in and to the on, the applications, and any and all Letters Patent or similar foreign or domestic legal protection |
| [X] [] | in the United States in all other countries or jurisdictions; |

"NOW THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, we transfer to Assignee, its successors and assigns, effective as of <u>October 11, 2013</u>, our entire right, title and interest in the above named countries and jurisdictions in and to the following including the right to sue for past infringement: the invention, the above-identified applications, all provisional applications from which any of the above-identified applications claim priority, corresponding domestic and foreign applications, any continuation, division, renewal, or substitute for the applications, all Letters Patent, any reissue, re-examination, or similar legal protection issuing related to the Letters Patent, and all rights and benefits under any applicable treaty or convention, and I/we authorize the Director of the United States Patent and Trademark Office or foreign equivalent to issue the Letters Patent or similar legal protection to the Assignee."

We authorize the Assignee, its successors and assigns, to insert in this instrument the filing date(s) and application numbers when ascertained. We further authorize the Assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent or similar legal protection, in its own name if desired, in the above named countries and jurisdictions and appoint Assignee the common representative in the above identified international application and any international application for the invention.

We represent to the Assignee, its successors and assigns, that we shall not execute any writing or do any act whatsoever conflicting with this Assignment. We, our executors or administrators, will at any time upon request, without additional consideration, but at the expense of the Assignee, its successors and assigns, execute and deliver to Assignee or its legal representatives such additional writings and do such additional acts as the Assignee, its successors and assigns, may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries and jurisdictions, including without limitation providing testimony in any related interference, litigation or proceeding. To the extent that we, our executors or administrators are unable or unavailable to execute and deliver to Assignee or its legal

representatives such additional writings and do such additional acts as Assignee, its successors and assigns may deem desirable to perfect its enjoyment of this grant, and render all assistance in making application for and obtaining, maintaining, and enforcing the Letters Patent or similar legal protection on the invention in any and all countries and jurisdictions, we, our executors or administrators hereby authorize Assignee, its successors and assigns to act on our behalves.

| | (Signature) Oh Byoung KWON (Inventor / Assignor) 2014.09.17 Date |
|---|---|
| | (Signature) Chul Jin KIM (Inventor / Assignor) 2014.09.17 Date |
| ~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~ | (Signature) Jae Hyuk LEE (Inventor / Assignor) 2014.09.17 Date |

(Signature)

Ki Mun PAIK (Inventor / Assignor)

2014.09.17 Date

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